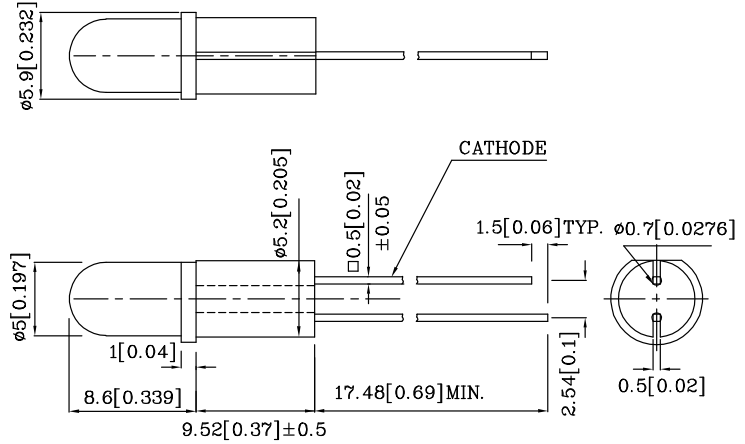


Features

- LED FIRMLY HELD BY SPACER-NO ADDITIONAL FIXTURING OR GLUEING NECESSARY.
- SUITABLE FOR BACK PANEL ILLUMINATION, CIRCUIT BOARD INDICATOR, LED INDICATOR.
- UL RATING:94V-0.
- HOUSING MATERIAL:TYPE 66 NYLON.
- RoHS COMPLIANT.



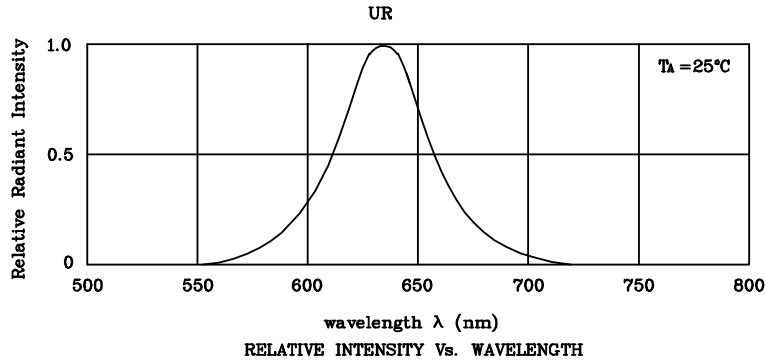
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.

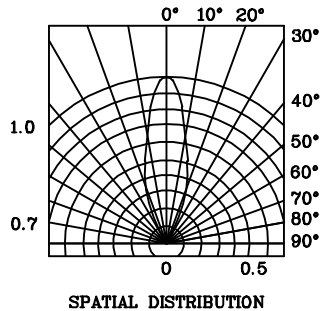
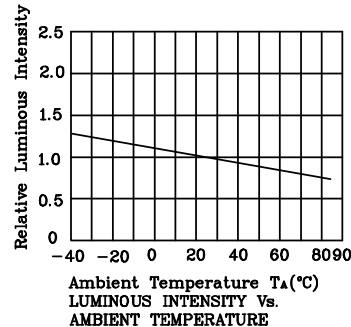
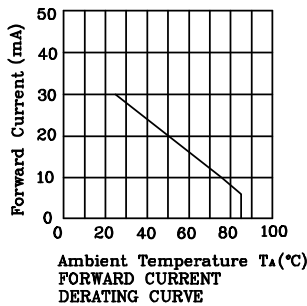
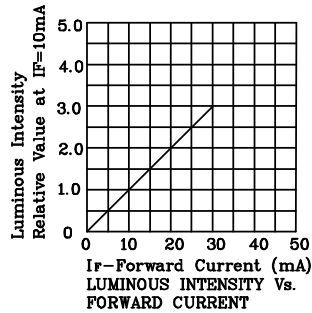
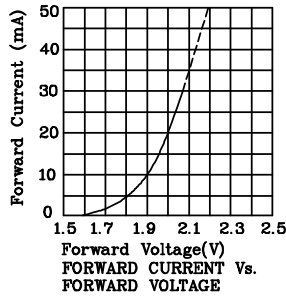
Absolute maximum ratings (TA=25°C)		UR (GaAsP/ GaP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	160	mA
Power Dissipation	P _T	105	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		UR (GaAsP/ GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	1.9	V
Forward Voltage (Max.) (I _F =10mA)	V _F	2.5	V
Reverse Current (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission (I _F =10mA)	λ _P	627	nm
Wavelength of Dominant Emission (I _F =10mA)	λ _D	625	nm
Spectral Line Full Width At Half-Maximum (I _F =10mA)	Δλ	45	nm
Capacitance (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =10mA) mcd		Wavelength nm λ _P	Viewing Angle 2θ 1/2
				min.	typ.		
XNM1LUR12D9.52	Red	GaAsP/GaP	Red Diffused	8	44	627	30°
Published Date : MAY 04,2005 Drawing No : XDSA7891 V1 Checked : B.L.LIU P.1/3							



❖ UR



Remarks:

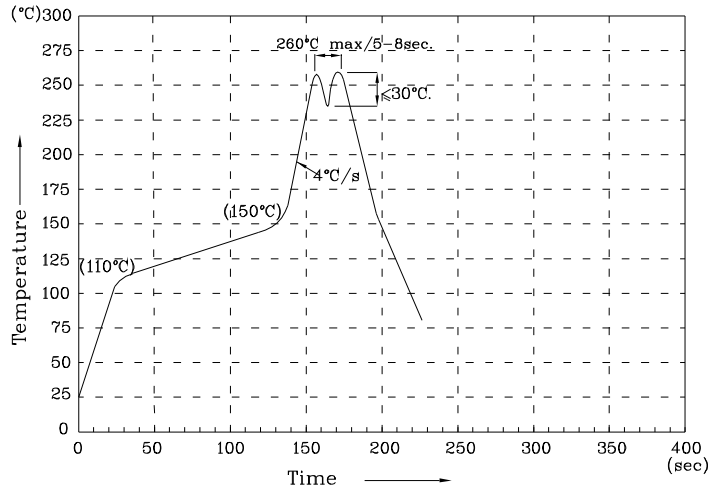
If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XNM1LUR12D9.52

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85 degree°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.No more than once.